

PCN Number:	20261020001.1	PCN Issued	October 21, 2026
Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet update and TI Mexico (FMX) as an additional Assembly site for select devices		Sample request deadline:	December 20, 2026
		Estimated 1st ship date:	January 19, 2027
Sample requests received after December 20, 2026 will not be supported.			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling Design Data Sheet/Electrical Specification Wafer Fab Site Wafer Fab Material Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, TIB) and TI Mexico (FMX) as assembly site option for select devices as listed below in the product affected section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
FFAB	BPSLM.7.1	200mm	RFAB	TIB	300mm

The die was also changed as a result of the process change.

Construction Differences are as follows:

	Current	Additional
Assembly Site	TIEMA	FMX
Wire bond diam/type	Au, 0.9 mil	Cu, 0.8 mil
Leadfinish	Matte Sn	NiPdAu
Mount compound	4213245	4225839
Mold compound	8095179	4211880
Marking – Top		
Marking - Bottom		

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history shown below. The links to the

revised datasheets are available in the table below.

LM317L

SLCS144G – JULY 2004 – REVISED AUGUST 2026



Changes from Revision F (December 2024) to Revision G (August 2026)	Page
Updated legacy and new chip information throughout the document.....	1
Removed output voltage range of the legacy chip from the <i>Features</i> section.....	1
Changed the input regulation per input voltage change from 0.01% to 0.007% in the <i>Features</i> section to reflect new chip (CSO: RFB) specs.....	1
Changed the typical ripple rejection at 120Hz spec from 80dB to 71.5dB in the <i>Features</i> section to reflect new chip (CSO: RFB) specs.....	1
Removed ripple rejection at 100kHz spec from the <i>Features</i> section.....	1
Added device package options to the <i>Features</i> section.....	1
Updated <i>Applications</i> section.....	1
Updated the <i>Description</i> section to reflect new chip (CSO: RFB) specs.....	1
Changed output voltage maximum from 32V to 37V in the <i>Description</i> section to reflect new chip (CSO: RFB) specs.....	1
Added new chip (CSO: RFB) specs to the Absolute Maximum Ratings.....	4
Added new chip (CSO: RFB) specs to the ESD Ratings.....	4
Added new chip (CSO: RFB) specs to the Recommended Operating Conditions.....	4
Added new chip (CSO: RFB) specs to the Thermal Information.....	5
Updated Thermal Information to two tables for clarity.....	5
Added new chip (CSO: RFB) specs to the Electrical Characteristics.....	5
Updated titles of <i>Typical Characteristics</i> graphs for legacy chip (CSO: SHE & CSO: TID).....	7
Added <i>Typical Characteristics</i> graphs for new chip (CSO: RFB).....	7
Updated <i>Overview</i> section to reflect new chip (CSO: RFB) specs.....	9
Removed mention of specific output voltage range and bias current in the <i>Overview</i> section, instead added a reference the <i>Electrical Characteristics</i> table, where the specs can be found.....	9
Updated <i>NPN Darlington Output Drive</i> with link to the <i>Recommended Operating Conditions</i>	10
Updated <i>Operation With Low Input Voltage</i> with a link to the <i>Recommended Operating Conditions</i>	10
Updated <i>Operation at Light Loads</i> with a link to the <i>Electrical Characteristics</i>	10
Updated <i>Operation in Self Protection</i> for clarity.....	10
Updated the maximum input range example value from 32V to 37V in the <i>Design Requirements</i> to reflect new chip (CSO: RFB) specs.....	11
Updated <i>Adjustment Terminal Capacitor</i> section to mention C _{ADJ}	12
Updated adjustment current from 50μA to 44μA in the <i>Output Voltage</i> section to reflect new chip (CSO: RFB) specs.....	12
Changed position of <i>Input Short Protection</i> to before <i>Ripple Rejection</i> within the <i>Detailed Design Procedure</i> ..	12
Updated <i>Ripple Rejection</i> with a link to the <i>Adjustment Terminal Capacitor</i> section.....	12
Updated <i>Application Curve</i> to specify legacy chip performance.....	12
Added note to <i>0V to 30V Regulator Circuit</i>	13
Added note to <i>Slow-Turn On 15V Regulator Circuit</i>	14
Added note to <i>Current-Limited 6V Charger</i>	15
Added note to <i>High-Current Adjustable Regulator</i>	16
Updated the maximum input voltage from 32V to 37V in the <i>Power Supply Recommendations</i> section to reflect new chip (CSO: RFB) specs.....	17
Added a link to the <i>Recommended Operating Conditions</i> table in the <i>Power Supply Recommendations</i> section.....	17
Updated <i>Layout Guidelines</i> to give more detailed guidance about capacitor placement.....	17
Added SOIC layouts to the <i>Layout Example</i> section.....	17
Updated the <i>Device Nomenclature</i> for clarity, included distinction based on CSO.....	19

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
LM317L	SLCS144F	SLCS144G	https://www.ti.com/product/LM317L

Qual details are provided in the Qual Data Section.

Reason for Change: Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• These devices include new die based on new schematic in a new process flow. • Physical aspects of the device have changed • Device quality has improved • Request the Supporting Data Packet and review updated Datasheets for more details on the changes. Evaluating samples is encouraged.																												
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> </tr> </tbody> </table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change																				
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Changes to product identification resulting from this PCN:	Fab Site Information <table border="1"> <thead> <tr> <th>Chip Site</th> <th>Chip Site Origin Code (20L)</th> <th>Chip Site Country Code (21L)</th> <th>Chip Site City</th> </tr> </thead> <tbody> <tr> <td>FFAB</td> <td>TID</td> <td>DEU</td> <td>Freising</td> </tr> <tr> <td>RFAB</td> <td>RFB</td> <td>USA</td> <td>Richardson</td> </tr> </tbody> </table> Die Rev: <table border="1"> <thead> <tr> <th>Current</th> <th>New</th> </tr> </thead> <tbody> <tr> <td>Die Rev [2P] C</td> <td>Die Rev [2P] A</td> </tr> </tbody> </table> Assembly Site Information <table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (23L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>TI Melaka</td> <td>CU6</td> <td>MYS</td> <td>Melaka</td> </tr> <tr> <td>TI Mexico</td> <td>MEX</td> <td>MEX</td> <td>Aguascalientes</td> </tr> </tbody> </table> Sample product shipping label (not actual product label): 	Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	FFAB	TID	DEU	Freising	RFAB	RFB	USA	Richardson	Current	New	Die Rev [2P] C	Die Rev [2P] A	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	TI Melaka	CU6	MYS	Melaka	TI Mexico	MEX	MEX	Aguascalientes
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Products Affected:	
LM317LCDR	LM317LIDR

Qualification Report

LM317L

Approve Date 05-AUGUST -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LM317LCDR	QBS Package, Process Reference: MC33063AQDRQ1	QBS Package Reference: UA78L15ACDRM3
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: LM317LCDR	QBS Package, Process Reference: MC33063AQDRQ1	QBS Package Reference: UA78L15ACDRM3
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device LM317LCDR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2511-049

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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